

## ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises: a semiconductor chip having a first main surface, a second main surface, and a plurality of side surfaces; an extension portion which contacts and surrounds the side surfaces of the semiconductor chip; a base, which is capable of conducting heat generated by the semiconductor chip; an insulating film which is formed on the first face and the first main surface; a plurality of wiring patterns extended from electrode pads to the upper side of the first face of the extension portion; a sealing portion which is formed on the wiring patterns and insulating film; and a plurality of external terminals provided over the wiring patterns in a region including the upper side of the extension portion.